



深圳市诚强光电有限公司
Infrared Emitting Diode 红外线发射管



规 格 承 认 书

客户名称		红外线发射管实图 
业务联系人		
联系电话		

型号：3AWMC06A/S14

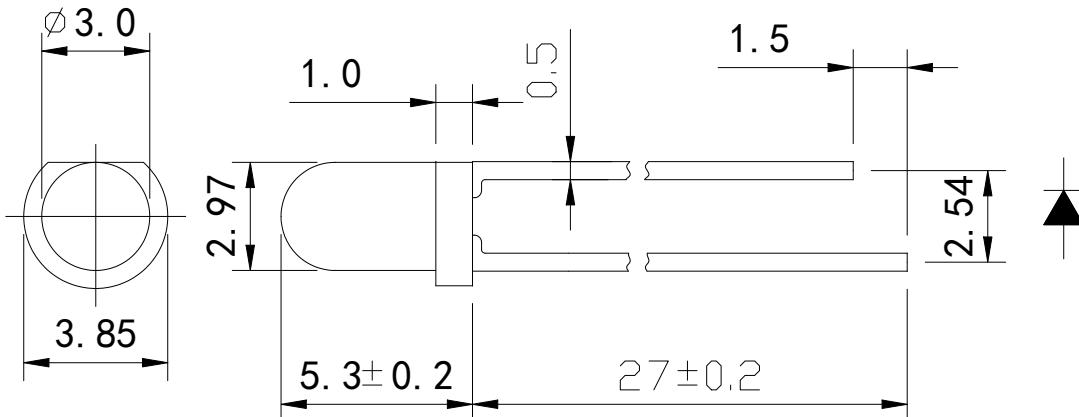
地址：深圳市宝安区石岩水田石龙仔工业区民营路4号诚强工业园
电话：13510504606 27661193 27865113 传真：0755-27865183
网址：www.szchq.net 邮箱：zgszchq@163.com

型号：3AWMC06A/S14

1、Features (特征)

- (1). 5*8.7mm ELLIPSE LAMP
(5*8.7mm 红外发射二极管)
- (2).LOWCURRENT REQUIREMENT
(低电流驱动)
- (3).LOWPOWER CONSUMPTION
(低功率消耗)
- (4).VERSATILE MOUNTING ON P.C. BOARD PANEL
(易安装)
- (5).LONG LIFE-SOLID STATE RELIABILITY
(寿命长)

2、Package Dimensions(封装尺寸)



Notes:

- (1).All dimensions are in millimeters.
(单位：毫米)
- (2).Tolerance is ± 0.25 unless otherwise noted.
(尺寸公差： ± 0.25 ,另有标注除外.)
- (3).Specifications are subject to change without notice.
(规格若有变动,恕不另行通知.)



深圳市诚强光电有限公司

Infrared Emitting Diode 红外线发射管

型号：3AWMC06A/S14

3、Electrical / Optical Characteristics at TA=25°C (25°C环境下之电性/光学特性)

Parameter(参数)	Symbol (符号)	Min. (最小值)	Typ. (规格值)	Max. (最大值)	Units (单位)	TestConditions (测试条件)
Forward Voltage (正向电压)	VF	--	1.2	1.35	V	IF=20mA
Forward Voltage	VF		1.5	1.6		IF=100mA
Peak Emitting Wavelength (峰值波长)	λ_p	--	940	--	nm	IF=20mA
Spectral Line Half Width (光谱半宽度)	$\Delta\lambda$	--	20	--	nm	IF=20mA
Reverse Current (反向电流)	IR	--	--	10	uA	VR=5V
Axial Radiant Intensity (辐射强度)	I_o		12	18--	mW/sr	IF=80mA
Tenninal Capacitance (结电容)	Ct	--	20	--	pF	F=1MHZ
Half Intensity Angle (角度)	$2\theta_{1/2}$	--	30	--	deg	IF=20mA
Shoot distance (发射距离)		15		20	m	

4、Absolute Maximum Ratings at TA=25°C(在25°C环境下之最大绝对额定值)

Parameter(参数)	Symbol(符号)	Maximum Rating(最大值)	Units(单位)
Power dissipation (耗散功率)	PD	100	mW
Aerage Forward Current(正向电流)	I_F	80	mA
Peak Forward Current(Duty=0.1,1KHZ) (正向电流峰值)	$I_{PF}(Peak)$	1	A
Reverse Voltage(反向电压)	V_R	5 V	
Operating Temperature Range (工作温度)	Topr	-20°C To +65°C	
Storage Temperature Range (贮藏温度)	Tstg	-40°C To +80°C	
Lead Solder Temperature(2)(焊接温度)	Tsol	260°C for 3 seconds	

Note:

(1).1/10 Duty Cycle, 0.1ms Pulse Width.

(1/10周期, 0.1ms脉宽)

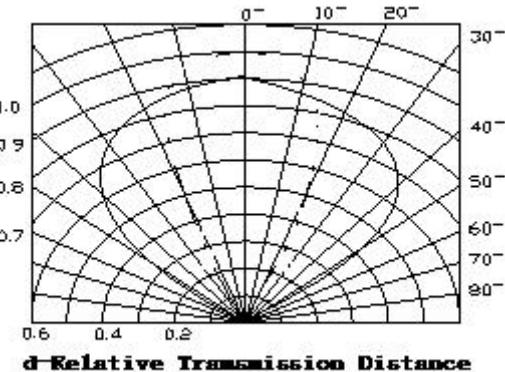
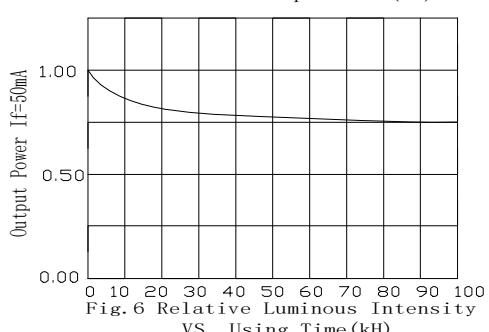
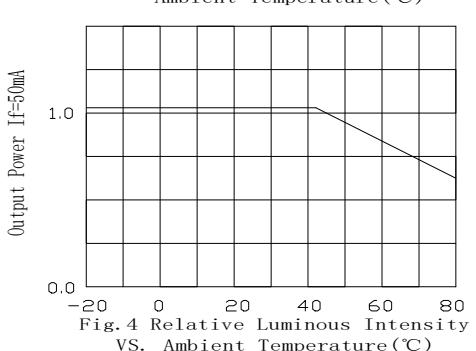
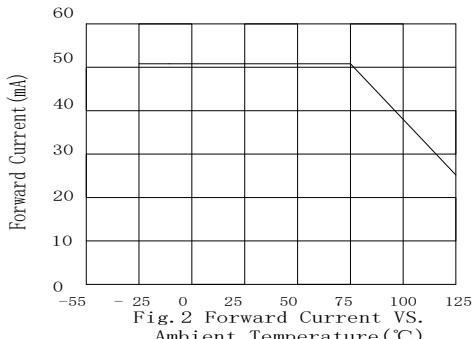
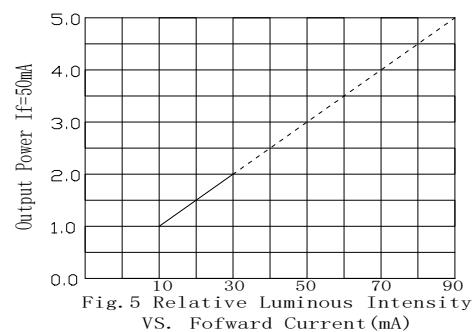
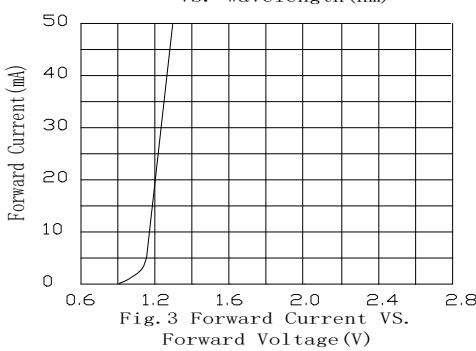
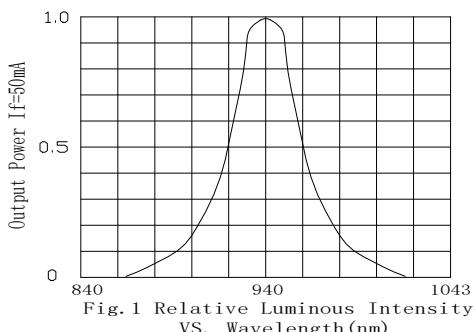
(2).The production accord with the demand of ROHS.

(此产品符合ROHS要求.)

地址: 深圳市宝安区石岩水田石龙仔工业区民营路4号诚强工业园
电话: 13510504606 27661193 27865113 传真: 0755-27865183
网址: www.szchq.net 邮箱: zgszchq@163.com

型号：3AWMC06A/S14

5、Graphs





深圳市诚强光电有限公司

Infrared Emitting Diode 红外线发射管

型号：3AWMC06A/S14

6..CAUTIONS: (注意事项)

1.Lead Forming & Assembly 引脚成型和组装

- Lead forming or bending must be done before soldering, at normal temperature.
引脚成型或弯曲必须在室温条件下焊接前进行
- During lead forming, the leads should be bent at a point at least 3mm from the base of LED lens. 在引脚成型时，弯脚处应该距离二极管晶体至少 3mm 的地方操作。
- Do not use the base of the lead frame as a fulcrum during lead forming.
在引脚成型时不要使用引脚框架的底座作为支点。
- Avoid bending the leads at the same point more than once.
避免在同一个弯脚超过一次。
- During assembly on PCB, use minimum clinch force possible to avoid excessive mechanical stress. 在 PCB 上组装时，尽可能用最小的按压力来避免过度的机械力。

2.LED Mounting Method 发射二极管固定方式

- The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. 在安装配件时二极管的脚距必须与 PCB 上的固定孔位间距一致
- When soldering wire to the LED. Use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit.
在给二极管焊接时，使用单独的热缩管对暴露的引脚绝缘，以防止意外短路。
- Use stand-offs or spacers to securely position the LED above the PCB.
应用备用或隔离装置将 LED 固定 PCB 上方

3.Soldering

- When soldering, the soldering iron needs to be at least 3mm away from the epoxy edge.
After soldering, allow at least 3 minutes for LEDs to cool back to normal temperature. DO not apply any pressure to the epoxy encapsulation or the lead frame during the soldering process.
在焊接时烙铁需要离胶体边缘至少 3 毫米，在焊接后让 LED 冷却到正常温度（三分钟）
焊接过程中不要对胶体或引脚框架施加外任何压力。
- When using hand soldering iron, please solder once for less than 3 seconds at a Maximum Temperature of 300° C. When soldering a row of LED on a PCB. Please do not solder both Leads of a LED in sequence. (Solder all the positive lead first, then all the negative leads).
当手工焊接时烙铁温度最高在 300 度情况下焊接一次时间不超过 3 秒。当焊接一排 LED 在 PCB 上时，请不要依次同时焊接 LED 的两个脚。
- Do not dip the epoxy encapsulation part of LED into any soldering paste liquid.
不要将 LED 的环氧树脂封装部分浸入任何锡膏液体中。
- After soldering, do not adjust the location of the LED anymore.
在焊接后不要调整 LED 的位置。